



SOT2039-1(SC)

HWQFN32, thermal enhanced, very-very thin quad flat package, no leads, step-cut wettable flank, 0.5 mm pitch, 5 mm x 5 mm x 0.68 mm body

28 December 2020

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HWQFN32
Package style descriptive code	HWQFN (thermal enhanced very very thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	13-05-2020
Manufacturer package code	98ASA01607D

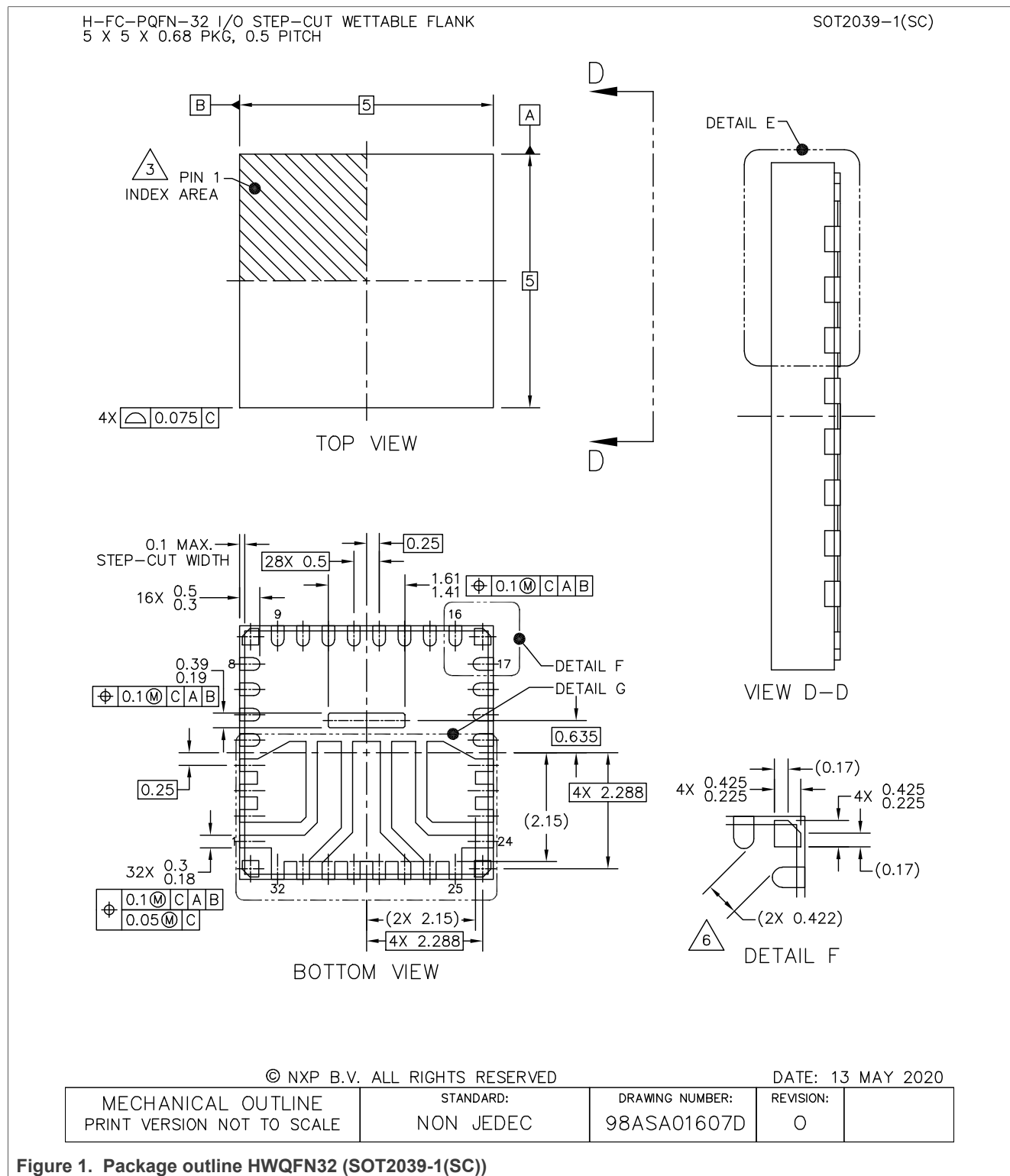
Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	4.925	5	5.075	mm
package width	4.925	5	5.075	mm
seated height	-	0.68	0.75	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	32	-	

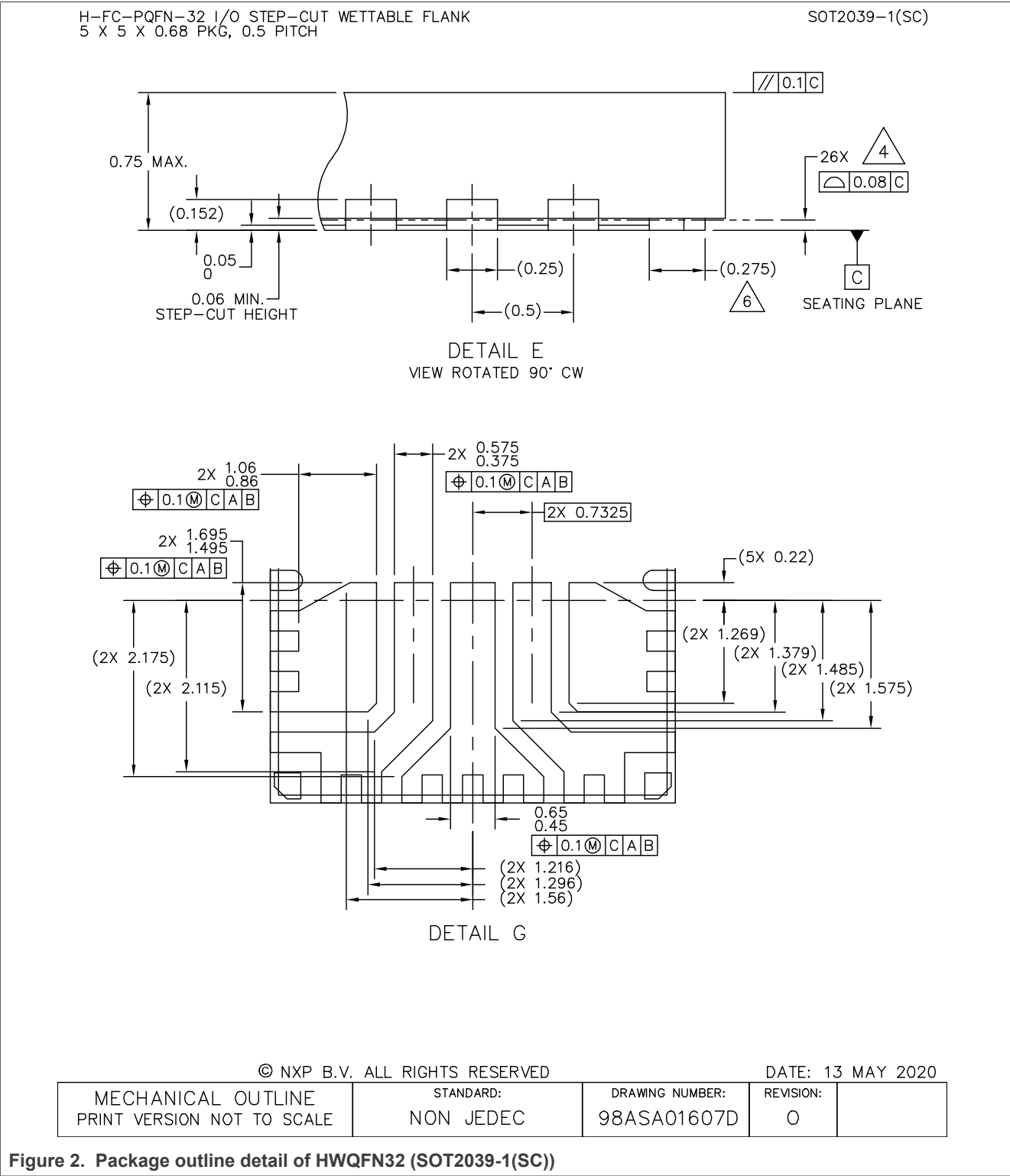


HWQFN32, thermal enhanced, very-very thin quad flat package, no leads, step-cut wettable flank, 0.5 mm pitch, 5 mm x 5 mm x 0.68 mm body

2 Package outline

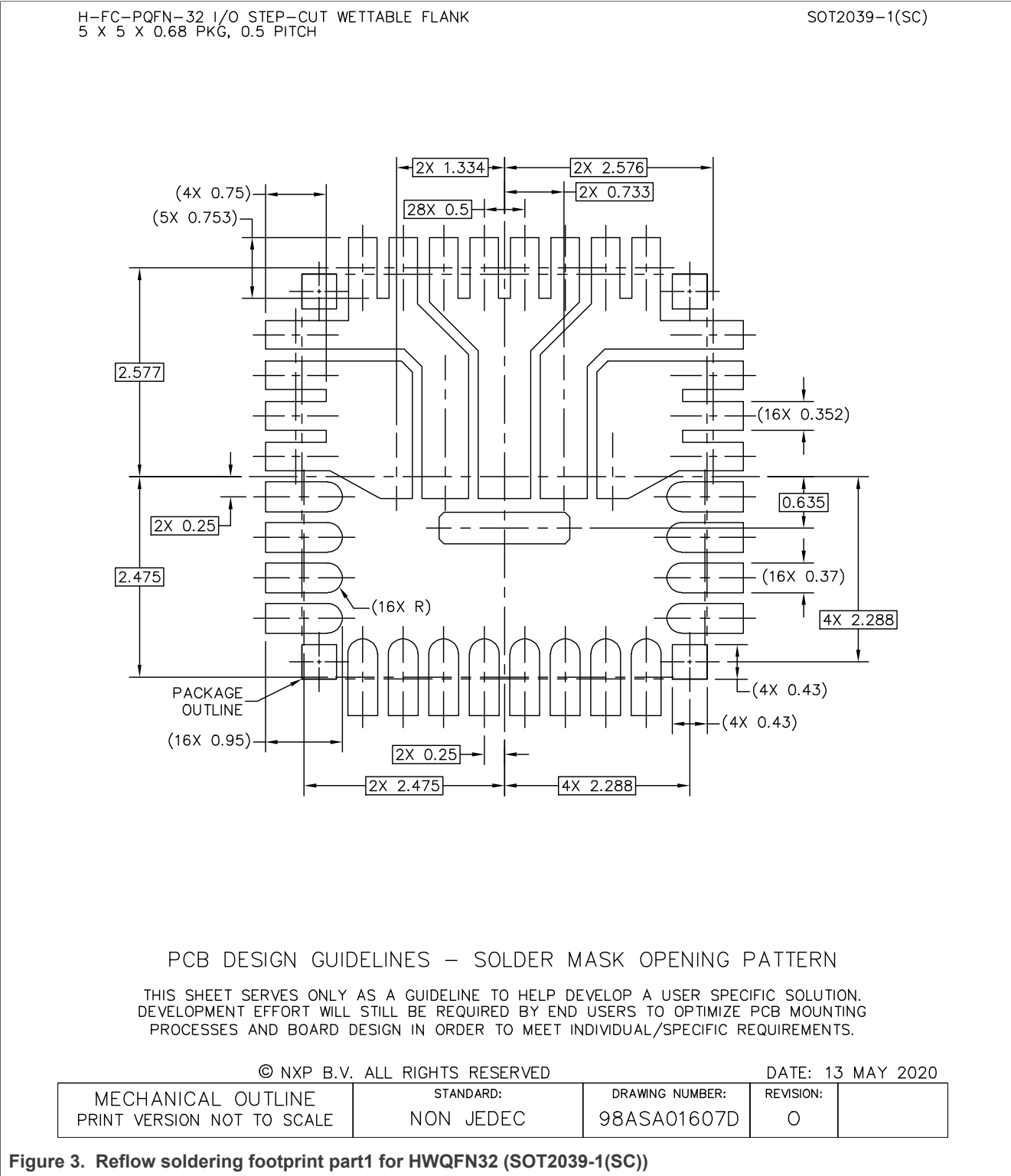


HWQFN32, thermal enhanced, very-very thin quad flat package, no leads, step-cut wettable flank, 0.5 mm pitch, 5 mm x 5 mm x 0.68 mm body

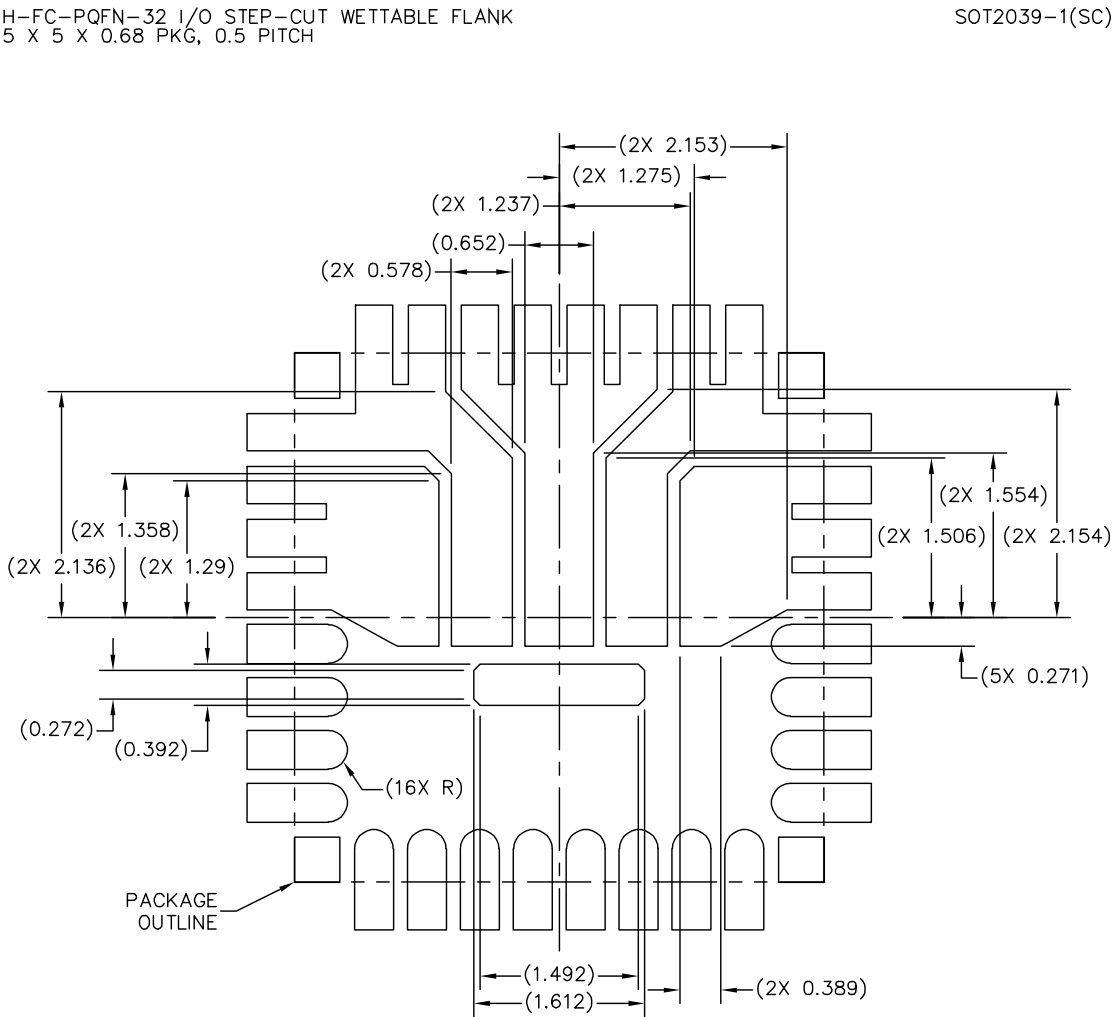


HWQFN32, thermal enhanced, very-very thin quad flat package, no leads, step-cut wettable flank, 0.5 mm pitch, 5 mm x 5 mm x 0.68 mm body

3 Soldering



HWQFN32, thermal enhanced, very-very thin quad flat package, no leads, step-cut wettable flank, 0.5 mm pitch, 5 mm x 5 mm x 0.68 mm body



PCB DESIGN GUIDELINES – SOLDER MASK OPENING PATTERN

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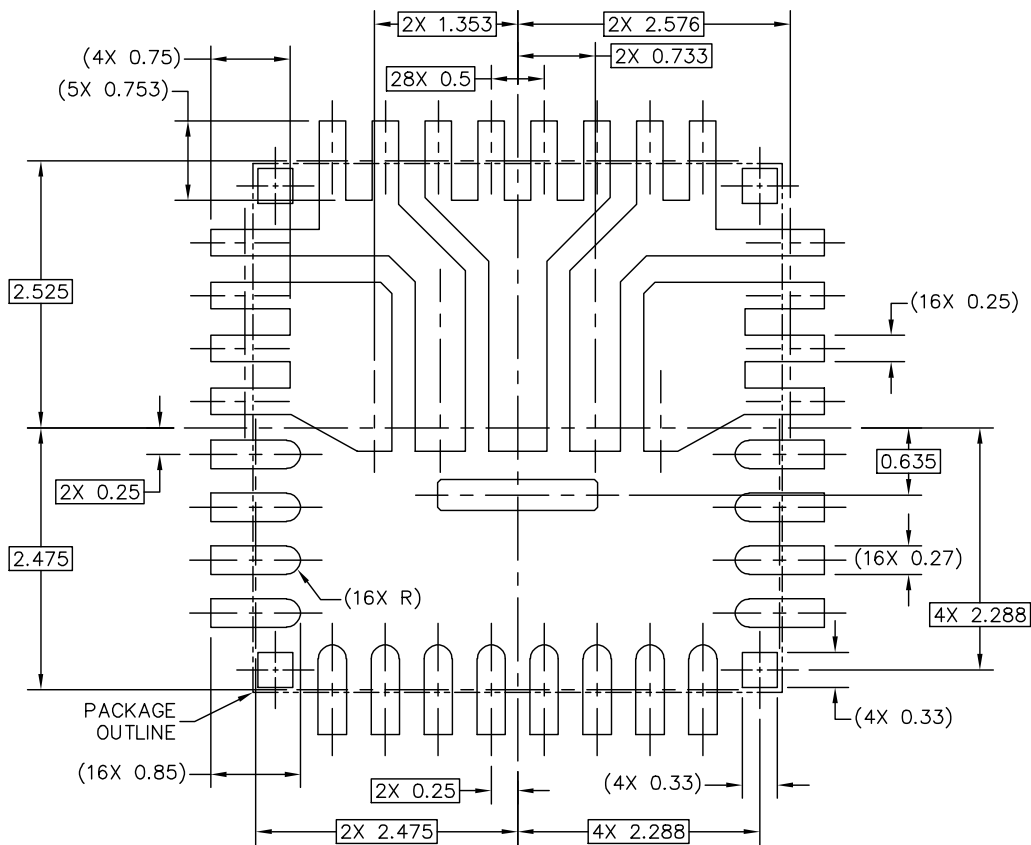
MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01607D	REVISION: O	
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Figure 4. Reflow soldering footprint part2 for HWQFN32 (SOT2039-1(SC))

HWQFN32, thermal enhanced, very-very thin quad flat package, no leads, step-cut wettable flank, 0.5 mm pitch, 5 mm x 5 mm x 0.68 mm body

H-FC-PQFN-32 I/O STEP-CUT WETTABLE FLANK
5 X 5 X 0.68 PKG, 0.5 PITCH

SOT2039-1(SC)



PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREA

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Figure 5. Reflow soldering footprint part3 for HWQFN32 (SOT2039-1(SC))

HWQFN32, thermal enhanced, very-very thin quad flat package, no leads, step-cut wettable flank, 0.5 mm pitch, 5 mm x 5 mm x 0.68 mm body

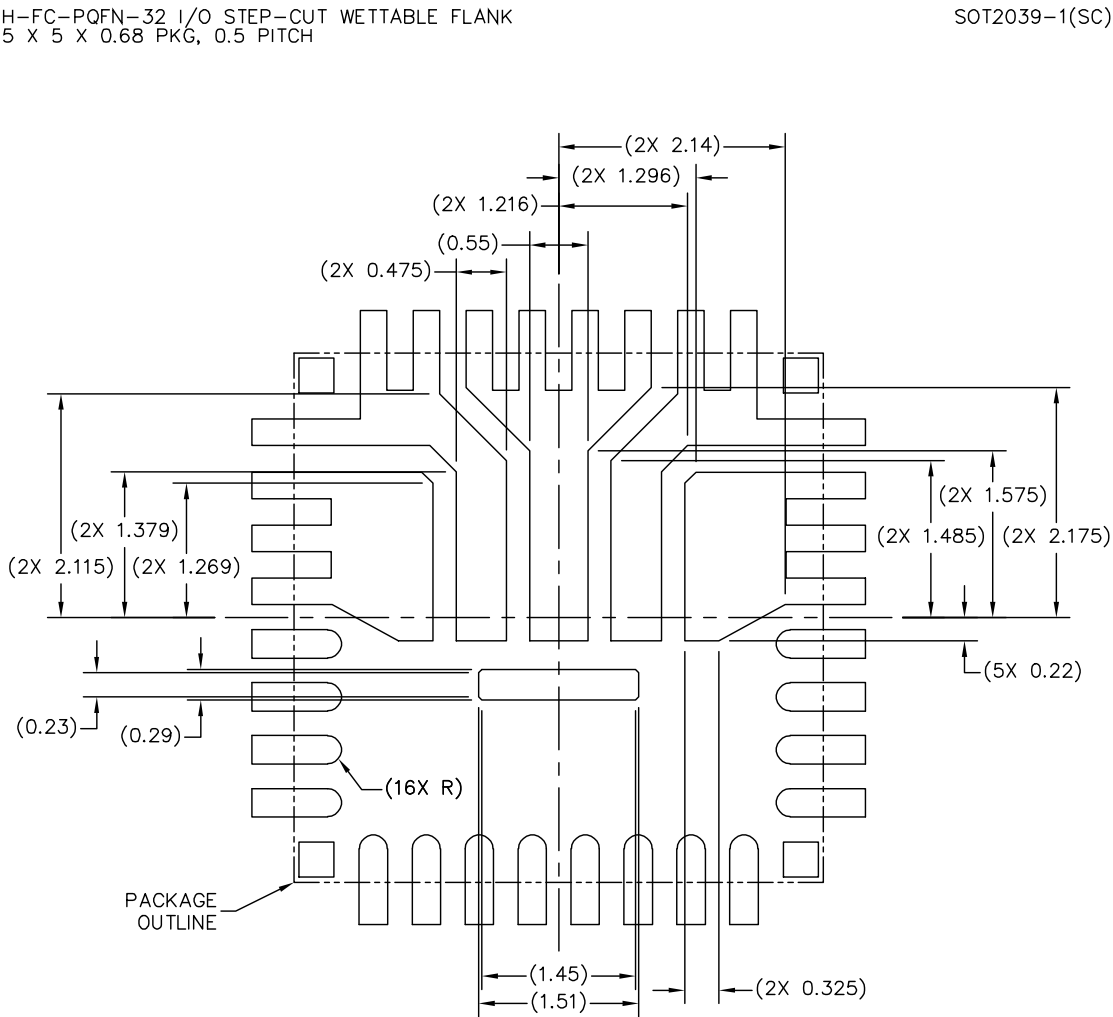


Figure 6. Reflow soldering footprint part4 for HWQFN32 (SOT2039-1(SC))

HWQFN32, thermal enhanced, very-very thin quad flat package, no leads, step-cut wettable flank, 0.5 mm pitch, 5 mm x 5 mm x 0.68 mm body

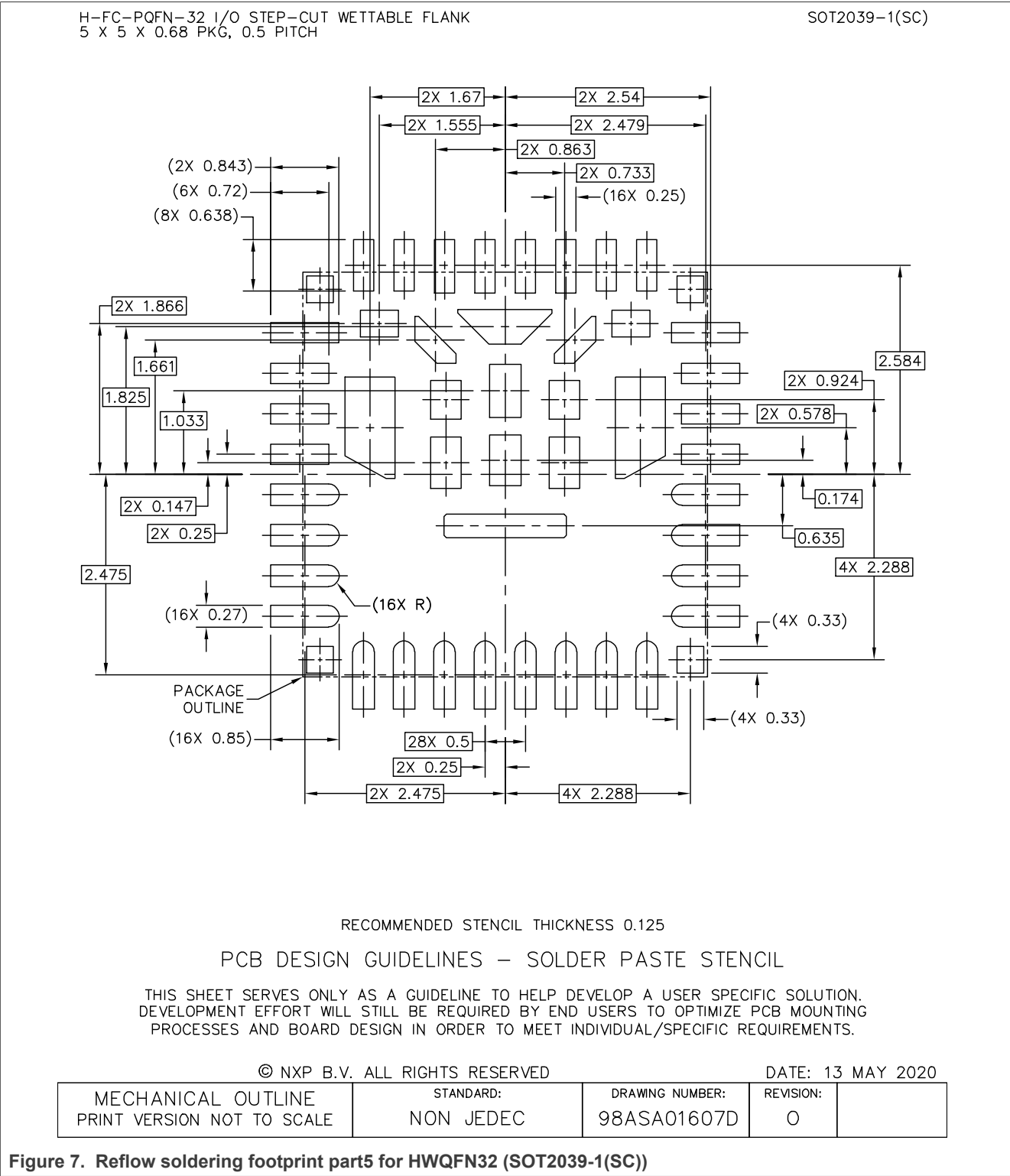
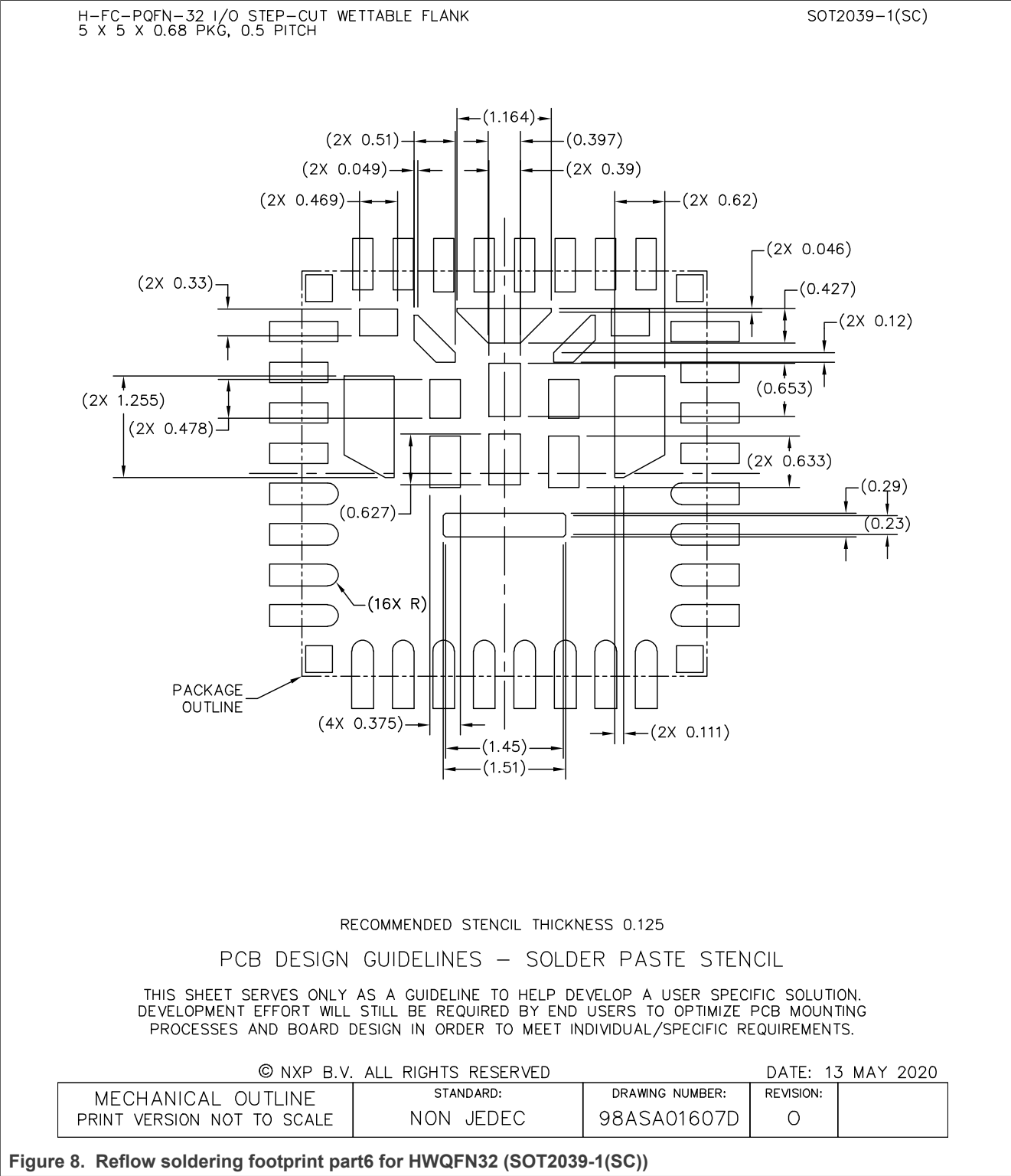


Figure 7. Reflow soldering footprint part5 for HWQFN32 (SOT2039-1(SC))

HWQFN32, thermal enhanced, very-very thin quad flat package, no leads, step-cut wettable flank, 0.5 mm pitch, 5 mm x 5 mm x 0.68 mm body



HWQFN32, thermal enhanced, very-very thin quad flat package, no leads, step-cut wettable flank, 0.5 mm pitch, 5 mm x 5 mm x 0.68 mm body

H-FC-PQFN-32 I/O STEP-CUT WETTABLE FLANK
5 X 5 X 0.68 PKG, 0.5 PITCH

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- NOTES:
- 1. ALL DIMENSIONS ARE IN MILLIMETERS.
 - 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
 - 3. PIN 1 FEATURE, SHAPE, SIZE AND LOCATION MAY VARY.
 - 4. COPLANARITY APPLIES TO LEADS AND DIE ATTACH PAD.
 - 5. MIN. METAL GAP SHALL BE 0.19 MM.
 - 6. ANCHORING PADS.

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Figure 9. Package outline note HWQFN32 (SOT2039-1(SC))

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